Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S78	2	"20040012930".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 11:50
S79	10	("5578525"|"5834848"|"6249053"|"6285083"|"6418615").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 11:47
S80	263	pad with wiring with short with circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 11:50
S81	31	(US-20010013425-$ or US-20010013653-$ or US-20020066948-$ or US-20020195272-$ or US-20030201309-$ or US-20040046252-$ or US-20050199995-$).did. or (US-5467253-$ or US-5578525-$ or US-5598036-$ or US-5704116-$ or US-5834848-$ or US-5953814-$ or US-6064114-$ or US-6217987-$ or US-6249053-$ or US-6285083-$ or US-6418615-$ or US-6512186-$ or US-6713880-$ or US-6714421-$ or US-6806560-$ or US-6469370-$ or US-6448783-$ or US-6229249-$ or US-6127729-$ or US-5869356-$ or US-5252844-$).did. or (JP-10098045-$ or JP-10173296-$ or JP-11204683-$).did.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 14:05
S82	1	"6854633".pn.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 14:05
S83	30	("20030051770" | "5128746" | "5211763" | "5385636" | "5417771" | "5482736" | "5611476" | "5851311" | "5880017" | "5904782" | "5989362" | "6053398" | "6059173" | "6059894" | "6063647" | "6100175" | "6118179" | "6168972" | "6180504" | "6184581" | "6204080" | "6234379" | "6259036" | "6260264" | "6276599" | "6283358" | "6293456" | "6297560" | "6352881" | "6402013").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 14:08
S84	1	"6622380".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 14:08

S85	30	("20030051770" | "5128746" | "5211763" | "5385636" | "5417771" | "5482736" | "5611476" | "5851311" | "5880017" | "5904782" | "5989362" | "6053398" | "6059173" | "6059894" | "6063647" | "6100175" | "6118179" | "6168972" | "6180504" | "6184581" | "6204080" | "6234379" | "6259036" | "6260264" | "6276599" | "6283358" | "6293456" | "6297560" | "6352881" | "6402013").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 14:11
S86	6	("5132879" | "5160779" | "5689091" | "5756377" | "5877553" | "5901436").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 14:45
S87	14	pad with wiring with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 14:46
S88	17	pad with (trace wiring) with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 14:47
S89	17	pad with (trace wiring) with shorting same substrate with (photoresistant mask solder near2 resist)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 14:47
S90	0	("2003/0201309").URPN.	USPAT	OR	ON	2005/12/06 14:49
S91	52	("5,107,328" "5,128,831" "5,138,434" "5,593,927" "5,677,566" "5,696,033" "5,704,116" "5,729,896" "5,739,585" "5,801,350" "5,815,000" "5,842,273" "5,851,845" "5,866,953" "5,891,753" "5,893,726" "5,898,224" "5,933,713" "5,938,956" "5,946,553" "5,958,100" "5,985,043" "5,986,209" "5,989,941" "5,990,566" "5,994,784").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S92	50	("6,008,070" "6,008,014" "6,018,249" "6,020,629" "6,025,728" "6,028,365" "6,046,496" "6,048,744" "6,048,755" "6,049,125" "6,066,514" "6,072,233" "6,072,236" "6,075,288" "6,081,429" "6,089,920" "6,094,058" "6,097,087" "6,103,547" "6,107,122" "6,107,680" "6,117,382" "6,124,634" "6,150,717" "6,159,764").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S93	22	("6,326,687" "6,326,697" "6,326,698" "6,329,220" "6,329,222" "6,331,221" "6,331,453" "6,332,766" "6,451,709" "6,589,820" "6,664,139").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03

S94	52	("6,172,419" "6,184,465" "6,189, 208" "6,198,172" "6,208,519" "6, 210,992" "6,215,175" "6,228,548" "6,228,687" "6,229,202" "6,246,108" "6,252,308" "6,258,623" "6,258,624" "6,259,153" "6,277,671" "6,284,571" "6,291,894" "6,294,839" "6,303,981" "6,303,985" "6,310,390" "6,314,639" "6,316,285" "6,326,242" "6,326, 244").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S95	176	S91 S92 S93 S94	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S96	14	(PCB insulat$4 near2 substrate dielectr$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) with (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S97	201	(PCB insulat$4 near2 substrate dielectr$4 near2 substrate) with (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S98	9	(PCB insulat$4 near2 substrate dielectr$4 near2 substrate) same (trace metal near2 (wiring layer line) (distribution redistribution signal) near2 (layer line)) and (solder near2 mask solder near2 resist resist near2 pattern) same(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S99	68	(PCB insulat$4 near2 substrate dielectr$4 near2 substrate) and (solder near2 mask solder near2 resist resist near2 pattern) and(solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03

S10 0	56	(PCB insulat$4 near2 substrate dielectr$4 near2 substrate) with pad with (mask solder near2 resist resist near2 pattern) with (solder near2 ball bump flip c4) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S10 1	655	pad with (prevent$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S10 2	76	(PCB insulat$4 near2 substrate dielectr$4 near2 substrate) with pad and pad with (prevent$4 avoid) with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S10 3	1031	insulat$5 with pad with solder with (ball bump c4 flip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S10 4	365	S103 and pad with (protect$5 prevent avoid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S10 5	348	S104 and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S10 6	3	("4489365" | "5237131" | "6011695").PN. OR ("6714421"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03

S10 7	83	("5107328" | "5128831" | "5138434" | "5593927" | "5677566" | "5696033" | "5704116" | "5729896" | "5739585" | "5801350" | "5815000" | "5842273" | "5851845" | "5866953" | "5891753" | "5893726" | "5898224" | "5933713" | "5938956" | "5946553" | "5958100" | "5985043" | "5986209" | "5989941" | "5990566" | "5994784" | "6008070" | "6018249" | "6020629" | "6025728" | "6028365" | "6046496" | "6048744" | "6048755" | "6049125" | "6066514" | "6072233" | "6075288" | "6081429" | "6089920" | "6094058" | "6097087" | "6103547" | "6107122" | "6107680" | "6117382" | "6124634" | "6150717" | "6159764" | "6172419" | "6184465" | "6189208" | "6198172" | "6208519" | "6210992" | "6215175" | "6228548" | "6228687" | "6229202" | "6246108" | "6258623" | "6258624" | "6259153" | "6277671" | "6284571" | "6291894" | "6294839" | "6303981" | "6303985" | "6310390" | "6314639" | "6316285" | "6326242" | "6326244" | "6326687" | "6326697" | "6326698" | "6329220" | "6329222" | "6331221" | "6331453" | "6332766" | "RE36469").PN. OR ("6622380").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S10 8	42	("2672681" | "3235414" | "3264146" | "3970239" | "4216035" | "4601763" | "4940181" | "5004508" | "5122200" | "5177134" | "5255839" | "5386624" | "5435481" | "5442240" | "5499756" | "5583747").PN. OR ("5704116"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S10 9	33	("4604644" | "5084961" | "5089440" | "5121190" | "5194930" | "5274913" | "5400950" | "5542601" | "5578525" | "5615477" | "5704116" | "5710071").PN. OR ("5953814"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S11 0	143	andujar.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S11 1	70	S110 and pad	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S11 2	3	("5391924" | "6011694" | "6054652").PN. OR ("6791199"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S11 3	56	("4791075" | "5216278" | "5474957" | "5602059" | "5650662" | "5663530" | "5679978" | "5710695" | "5737191").PN. OR ("6011694"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03

S11 4	1937	protect$4 with exposed with pad	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S11 5	1801	protect$4 with exposed with pad and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S11 6	424	protect$4 with exposed with pad with (insulat$3 dielectric) and (integrated near2 circuit IC chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S11 7	65	protect$4 with exposed with pad and "174"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S11 8	2	"6217987".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S11 9	1	"6217987".pn.	USPAT	OR	ON	2005/12/06 17:03
S12 0	46	("3356624" | "4504607" | "4510276" | "4615950" | "4713298" | "4750976" | "4752499" | "4820549" | "4888269" | "4902726" | "4948700" | "4990395" | "5009982" | "5021472" | "5055321" | "5055378" | "5061744" | "5137936" | "5175060" | "5302492" | "5519177" | "5532094" | "5741575" | "5753722" | "5948514").PN. OR ("6217987"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S12 1	14	("5321210" | "5322593" | "5337466" | "5426849" | "5590461" | "5628852" | "5686702" | "5745984" | "6049123" | "6214641").PN. OR ("6418615"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S12 2	2	"6418615".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S12 3	0	US005578525A	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03

S12 4	2	"5578525".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S12 5	80	"5,432,734"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S12 6	2	"5,432,734".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S12 7	28	("5578525").URPN.	USPAT	OR	ON	2005/12/06 17:03
S12 8	32	("20010013653" | "20020012234" | "4801998" | "5194934" | "5222014" | "5231036" | "5463229" | "5578525" | "5579207" | "5786589" | "5821532" | "5858815" | "5867368" | "5907151" | "5925898" | "5949655" | "5962810" | "5973337" | "5977624" | "6005965" | "6011310" | "6028354" | "6046070" | "6122009" | "6130448" | "6143981" | "6144507" | "6247229" | "6281568" | "6291884" | "6342406" | "6396043"). PN. OR ("6627864").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S12 9	1	"5,178,685".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S13 0	12	("5178685").URPN.	USPAT	OR	ON	2005/12/06 17:03
S13 1	118	(hole opening) with (solder near2 (resist mask) with trace)	USPAT	OR	ON	2005/12/06 17:03
S13 2	23	("3823469" | "4050621" | "4604644" | "4605153" | "4803450" | "4837609" | "5060844" | "5133495" | "5148265" | "5148266" | "5160409" | "5400220" | "5519580" | "5534127" | "5547740" | "5551627" | "5558271" | "5615477" | "5801446" | "5808874" | "5849750" | "5885849" | "6130448").PN. OR ("6465747").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S13 3	99	trace with pad with short with circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/06 17:03

S13 4	1	"6622380".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/12/06 17:03
S13 5	0	solde adj mask with flux and "174". ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S13 6	0	solder near2 mask with flux and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S13 7	0	solder near2 mask and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S13 8	7746	solder near2 mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S13 9	0	S138 and "174".ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S14 0	588	solder near2 mask same PCB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S14 1	339	S140 and (IC chip integrated adj circuit wafer die semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S14 2	178	S140 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03

S14 3	500	solder near2 mask same BGA	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S14 4	347	S143 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S14 5	302	S144 not S142	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S14 6	54	pad with circuit adj board with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S14 7	2	"6806560".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S14 8	15	("4786545" | "5055321" | "5278429" | "5473512" | "5519251" | "5756380" | "5816478" | "5834832" | "5872399" | "5925403" | "6197615" | "6286207" | "6288451" | "6323542" | "6344753").PN. OR ("6806560"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S14 9	347	S143 and (IC chip integrated adj circuit wafer die semiconductor).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 17:03
S15 0	21	(US-20010013425-$ or US-20020195272-$ or US-20030201309-$ or US-20010013653-$ or US-20040046252-$ or US-20020066948-$).did. or (US-6512186-$ or US-6217987-$ or US-6418615-$ or US-5704116-$ or US-5953814-$ or US-6713880-$ or US-6714421-$ or US-5578525-$ or US-6806560-$ or US-6249053-$ or US-6064114-$ or US-5598036-$ or US-5467253-$).did. or (JP-10173296-$ or JP-11204683-$). did.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 17:03

S15 1	0	JP-1098045-$.did.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 17:03
S15 2	1	JP-10098045-$.did.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 17:03
S15 3	0	JP-10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 17:03
S15 4	0	1998jp10098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 17:03
S15 5	0	1998jp1098045.ap,prai.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 17:03
S15 6	1	"6249053".pn.	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 17:03
S15 7	331	mother with board with PCB	US-PGPUB; USPAT; JPO	OR	ON	2005/12/06 17:03
S15 8	227	mother with board with PCB	USPAT	OR	ON	2005/12/06 17:03
S15 9	46	mother with board with interposer	USPAT	OR	ON	2005/12/06 17:03
S16 0	68	pcb with board with interposer	USPAT	OR	ON	2005/12/06 17:03
S16 1	19	("20020041489"| "4897918"| "5222014"| "5474458"| "5477933"| "5598036"| "5783870"| "5874776"| "5973930"| "5975409"| "5990545"| "6050832"| "6059579"| "6163462"| "6174175"| "6333563"| "6335491"| "6362437"| "6479760").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S16 2	18	("3541222"| "5477933"| "5530288" | "5759047"| "5834848"| "5973930" | "6002168"| "6050832"| "6059579" | "6088915"| "6163462").PN. OR ("6335491").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S16 3	23	("3777221"| "5375042"| "5477933" | "5535101").PN. OR ("5973930"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S16 4	6	substrate with eutectic with paste with solder with contact	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S16 5	7	board with eutectic with paste with solder with contact	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03
S16 6	7	board with eutectic with paste with contact	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03

S16 7	28	board with eutectic with paste with pad	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 17:03